

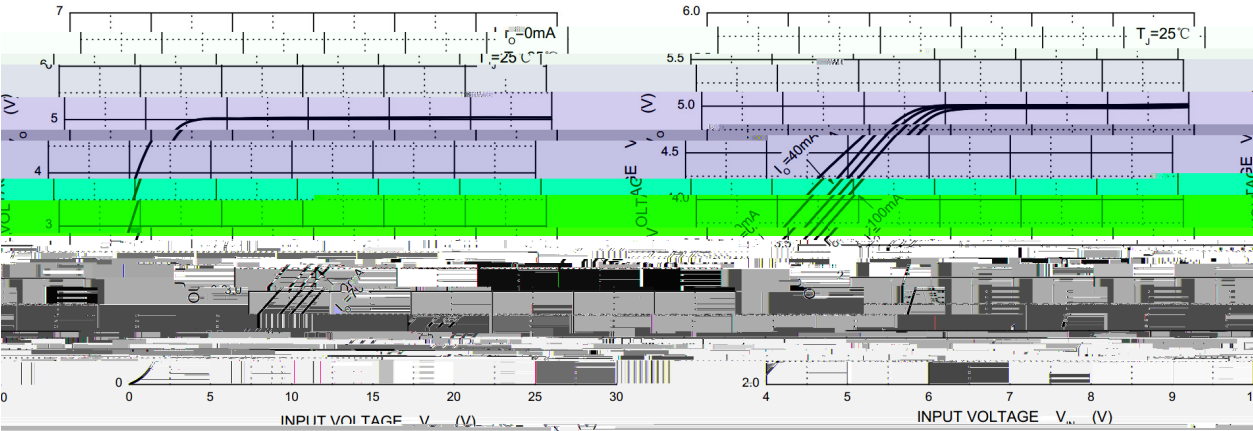
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Input voltage	V_I	36	V
Output current($V_I=8V$)	I_O	100	mA
Operating virtual Junction temperature	T_J	0~125	
Power Dissipation	P_D	500	mW
Storage temperature range	T_{stg}	-65~150	
Thermal resistance junction-ambient	$R_{\theta JA}$	200	$^{\circ}C/W$

/ Electrical Characteristics(Ta=25 $V_I=10V, I_O=40mA$ unless otherwise specified)

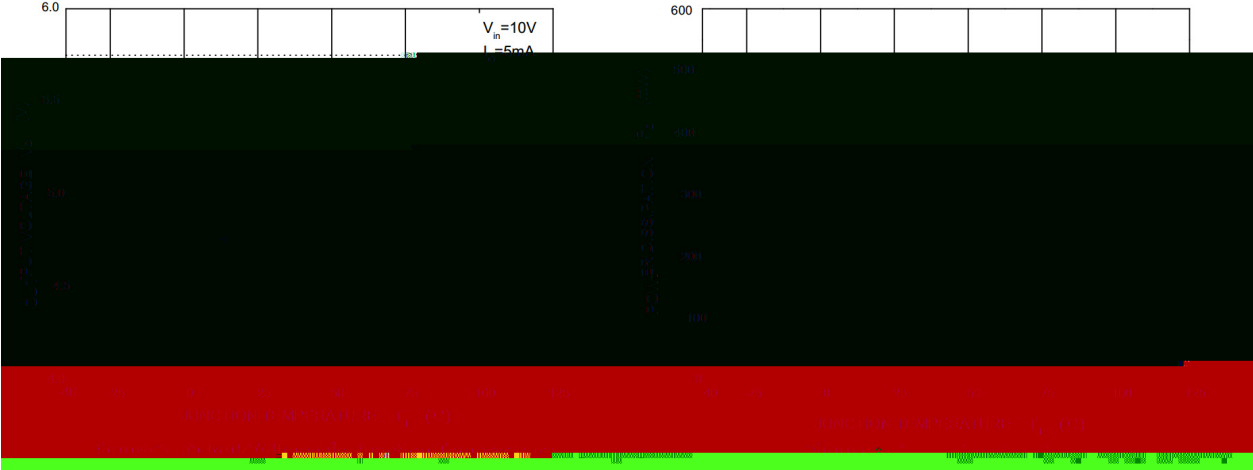
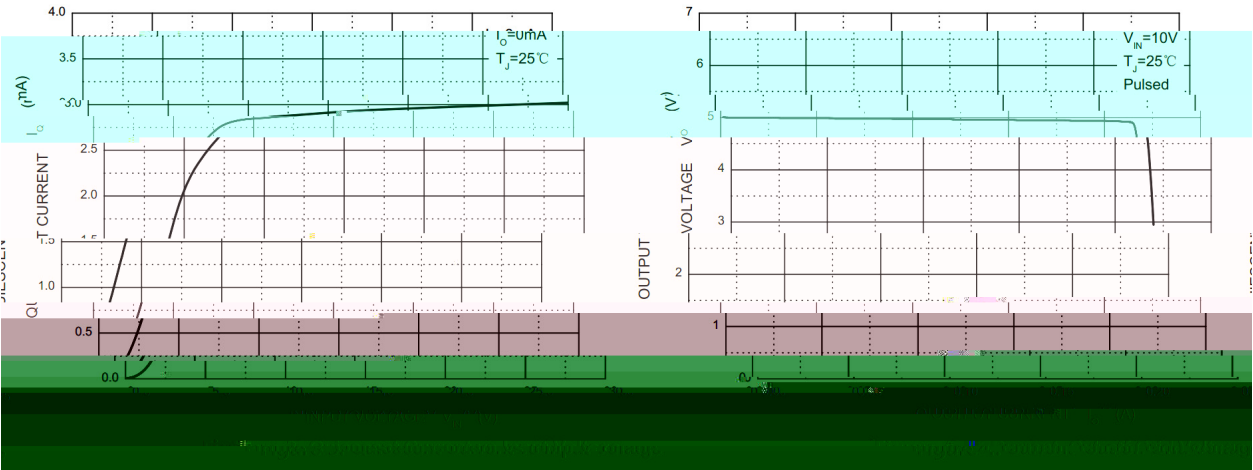
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Output voltage	V_O	$I_O=40mA$ $T_J=25^{\circ}C$	4.80	5.0	5.2	V
		$I_O=1mA$ to 40mA $V_I=7V$ to 20V	4.75	5.0	5.25	V
		$I_O=1mA$ to 70mA $V_I=10V$	4.75	5.0	5.25	V
Input regulation	ΔV_O	$V_I=7V$ to 20V $T_J=25^{\circ}C$		32	150	mV
		$V_I=8V$ to 20V $T_J=25^{\circ}C$		26	100	mV
Output regulation	ΔV_O	$I_O=1mA$ to 100mA $T_J=25^{\circ}C$		15	60	mV
		$I_O=1mA$ to 40 mA $T_J=25^{\circ}C$		8	30	mV
Ripple rejection	RR	$V_I=8V$ to 18V $f=120Hz$ $T_J=25^{\circ}C$	41	49		dB
Output noise voltage	V_N	$f=10Hz\sim 100KHz$ $T_J=25^{\circ}C$		42		μV
Dropout voltage	V_D	$T_J=25^{\circ}C$		2		V
Bias current	I_Q	$T_J=25^{\circ}C$		1	6	mA
		$T_J=125^{\circ}C$			5.5	mA
Bias current change	ΔI_Q	$V_I=8V$ to 20V			1.5	mA
		$I_O=1mA$ to 40mA			0.1	mA

/ Electrical Characteristic Curve



cs Figure 1. Output Characteristics

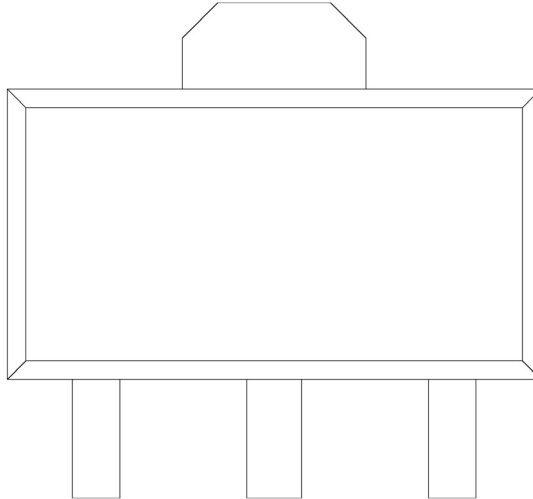
Figure 2. Dropout Characteristics



单位: 万元

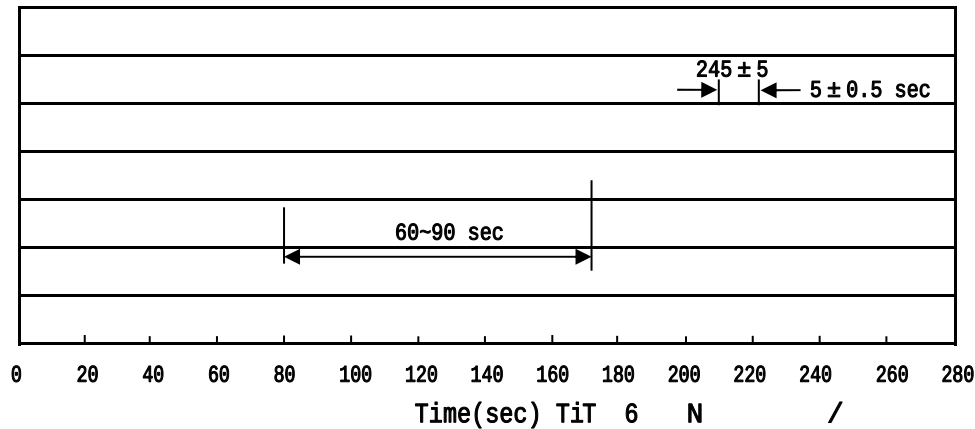


/ Marking Instructions



H
L05

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
SOT-89	1,000	7	7,000	6	42,000	7" ×12	180×120×180	390×385×205

/ Notices